$V_{RRM} = 6000 V$

 $I_{FAVM} = 250 A$

 $I_{FSM} = 3.6 \text{ kA}$

 $V_{F0} = 2.5 V$

 $r_F = 2.5 \text{ m}\Omega$

 $V_{DClink} = 3000 V$

Fast Recovery Diode

5SDF 02D6002

PRELIMINARY

Doc. No. 5SYA1108-02 Sep. 01

- · Patented free-floating silicon technology
- Low switching losses
- Optimized for use as snubber diode in high-voltage GTO converters
- Standard press-pack ceramic housing, hermetically cold-welded
- · Cosmic radiation withstand rating

Blocking

V_{RRM}	Repetitive peak reverse voltage	6000 V	Half sine wave, t_P = 10 ms, f = 50 Hz		
I _{RRM}	Repetitive peak reverse current	≤ 50 mA	$V_R = V_{RRM,} T_j = 125$ °C		
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	3000 V	100% Duty	Ambient cosmic radiation at	
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	3800 V	5% Duty	sea level in open air.	

Mechanical data (see Fig. 7)

ш	Mounting force mir	١.	10 kN
F _m	max	۲.	12 kN
а	Acceleration: Device unclamped Device clamped		50 m/s ² 200 m/s ²
m	Weight		0.25 kg
Ds	Surface creepage distance	≥	30 mm
Da	Air strike distance	≥	20 mm



On-state (see Fig. 2, 3)

I _{FAVM}	Max. average on-state current	250 A	Half sine wave, T _c = 85°C	
I _{FRMS}	Max. RMS on-state current	400 A		
I _{FSM}	Max. peak non-repetitive	3.6 kA	tp = 10 ms Before surge:	
	surge current	11.4 kA	tp = 1 ms $T_c = T_j = 125^{\circ}C$	
∫l ² dt	Max. surge current integral	65·10 ³ A ² s	tp = 10 ms After surge:	
		65·10 ³ A ² s	tp = 1 ms $V_R \approx 0 \text{ V}$	
V _F	Forward voltage drop	≤ 5 V	I _F = 1000 A	
V _{F0}	Threshold voltage	2.5 V	Approximation for $T_j = 125^{\circ}C$	
r _F	Slope resistance	2.5 mΩ	I _F = 2004000 A	

Turn-on (see Fig. 4, 5)

V _{fr} Peak forward recovery volta	≤ 370 V	di/dt = 1000 A/μs, T _j = 125°C
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Turn-off (see Fig. 6)

Irr	Reverse recovery current	≤	260 A	di/dt = 100 A/µs,	T _j = 125 °C,
Q _{rr}	Reverse recovery charge	≤	2000 μC	I _F = 1000 A,	$V_{RM} = 6000 V,$
E _{rr}	Turn-off energy	<	J	$R_S = 22 \Omega$,	$C_S = 0.22 \mu F$

Thermal (see Fig. 01)

Tj	Operating junction temperature range	-40125°C		
T _{stg}	Storage temperature range	-40125°C		
R _{thJC}	Thermal resistance junction to case	≤ 80 K/kW	Anode side cooled	
		≤ 80 K/kW	Cathode side cooled	F _m =
		≤ 40 K/kW	Double side cooled	10 12 kN
R _{thCH}	Thermal resistance case to heatsink	≤ 16 K/kW	Single side cooled	
		≤ 8 K/kW	Double side cooled	

Analytical function for transient thermal impedance.

$$Z_{\text{thJC}}(t) = \sum_{i=1}^{n} R_{i}(1 - e^{-t/\tau_{i}})$$

i	1	2	3	4			
R _i (K/kW) 20.95 10.57 7.15 1.33							
τ _i (s) 0.396 0.072 0.009 0.0044							
F _m = 10 12 kN Double side cooled							

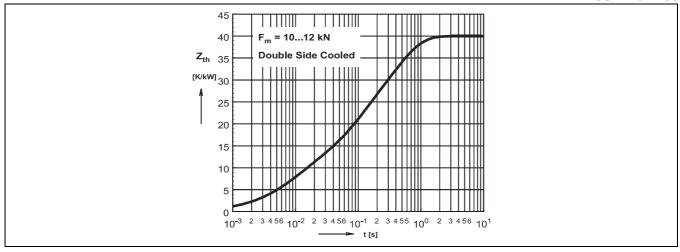


Fig. 1 Transient thermal impedance (junction to case) vs. time in analytical and graphical form (max. values).

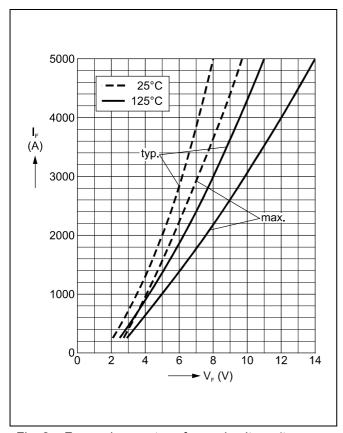


Fig. 2 Forward current vs. forward voltage (typ. and max. values).

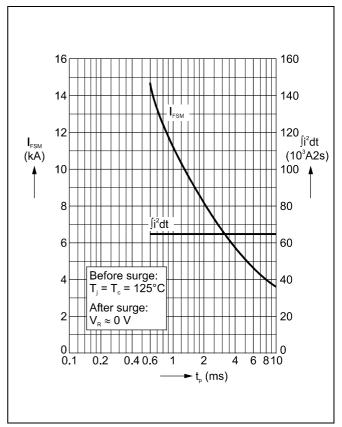


Fig. 3 Surge current and fusing integral vs. pulse width (max. values) for non repetitive, half-sinusoidal surge current pulses.

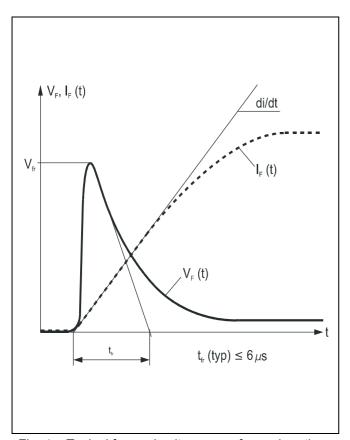


Fig. 4 Typical forward voltage waveform when the diode is turned on with a high di/dt.

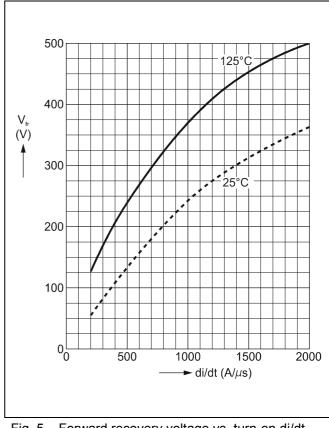


Fig. 5 Forward recovery voltage vs. turn-on di/dt (max. values).

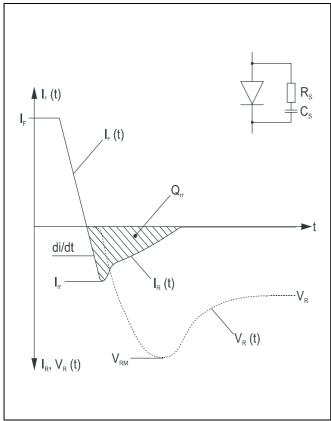


Fig. 6 Typical current and voltage waveforms at turn-off with conventional RC snubber circuit

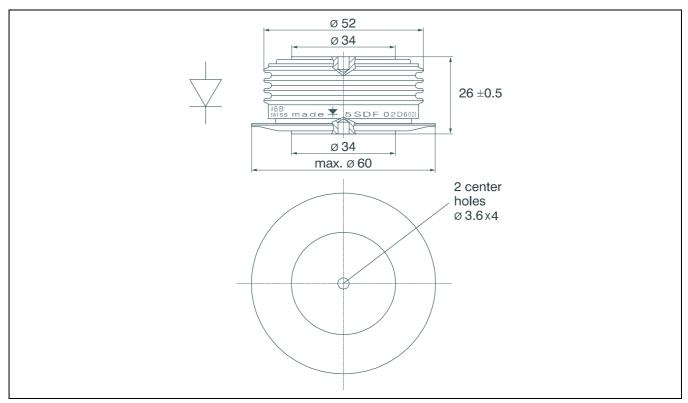


Fig. 7 Outline drawing. All dimensions are in millimeters and represent nominal values unless stated otherwise.

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